Electronic Supplementary Material (ESI) for Soft Matter.

Support Information

Processing and Characterization of Silver-Filled Conductive Polysulfide Sealants for Aerospace applications

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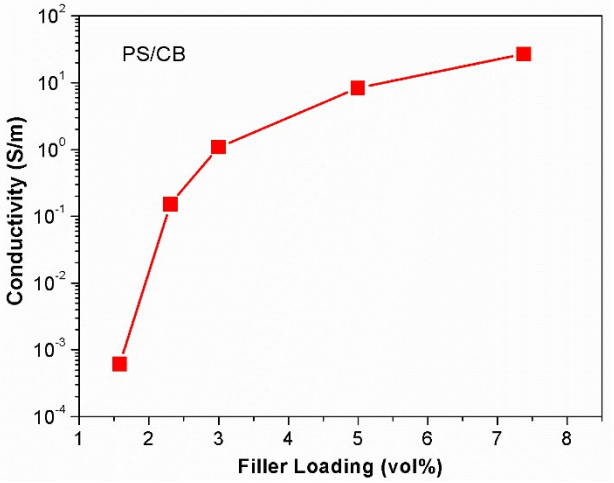

Figure S1. Conductivity of room temperature cured PS/CB sealants with different filler loadings.

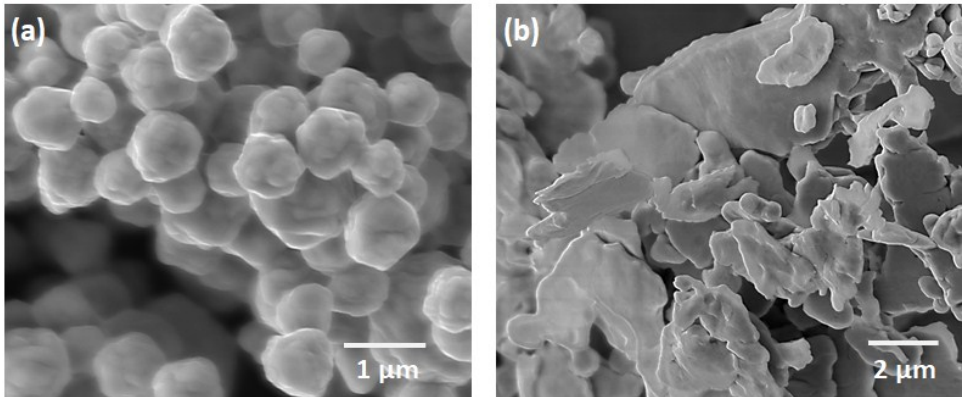

Figure S2. Conductivity of room temperature cured PS/CB sealants with different filler loadings.

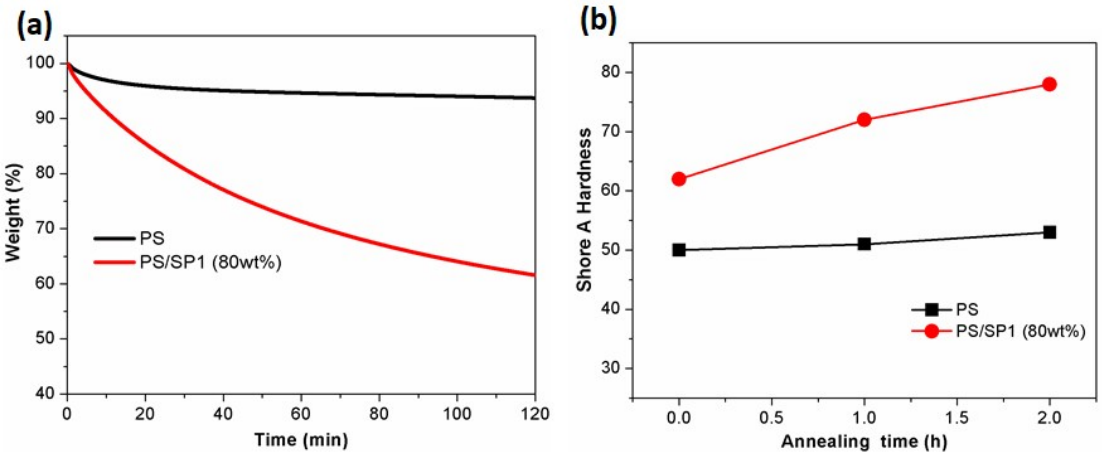

Figure S3. (a)TGA curves and (b) hardness change of PS and PS/SP1 (80wt%) sealants under isothermal annealing at 150°C with regards to time.

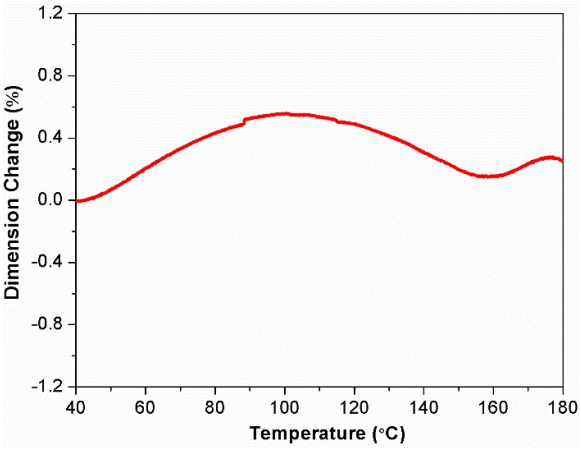

Figure S4. Dimension change of PS resin versus temperature.